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Home > Products > By Type > Sockets/Memory Card Products > Product Feature Selector > Product Details
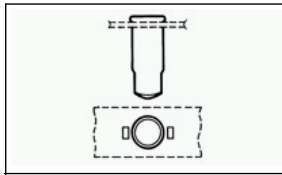
Product Details for 5645980   - 1

5645980   - 1

✔ Active

Discrete Sockets

RoHS Compliant   (Statement of Compliance)

Product Highlights:
- Socket
- Mating Pin Dia. Range = 1.07   - 1.24 mm
- Socket Length = 7.82 mm
- Sleeve Style = Bullet Nose
- Tin Sleeve Plating

View all Features

Quick Links
- Check Pricing & Availability
- Search for Tooling
- Product Feature Selector
- Contact Us About This Product

Documentation & Additional Information

Product Drawings:
- MINIATURE SPRING SOCKET ASSEMBLY   (PDF, English)

Catalog Pages/Data Sheets:
- None Available

Product Specifications:
- None Available

Application Specifications:
- None Available

Instruction Sheets:
- None Available

CAD Files:
- None Available

Additional Information:
- Product Line Information

Related Products:
- Tooling

List all Documents

Product Features   (Please use the Product Drawing for all design activity)

Product Type Features:
- Product Type = Socket
- Socket Length (mm [in])   = 7.82 [0.308]
- Sleeve Style   = Bullet Nose
- Sealant   = Without
- Sleeve Material = Copper
- Recommended Hole Size (mm [in]) = 2.59 [0.102]

Body Related Features:
- Mating Pin Dia. Range (mm [in])   = 1.07   – 1.24 [0.042   – 0.049]
- Spring Material = Beryllium Copper

Contact Related Features:
- Sleeve Plating   = Tin
- Contact Spring Plating   = Tin
- Contact Material   = Beryllium Copper

Configuration Related Features:
- Insertion Method   = Hand/Semi   - Automatic

Industry Standards:
- Government/Industry Qualification = No
- RoHS/ELV Compliance   = RoHS compliant, ELV compliant
- Lead Free Solder Processes   = Wave solder capable to 240°C, Wave solder capable to 260° C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin   - in - Paste capable to 245°C, Pin   - in - Paste capable to 260°C
- RoHS/ELV Compliance History = Always was RoHS compliant

Operation/Application:
- Application = Production

Packaging Related Features:
- Packaging Method   = Loose Piece

Other:
- Brand = AMP

Languages   : English | Deutsch | Español | Português (do Brasil) | ??????? | Italiano | ????   (??) | ??   (? ?) | ???
Country Sites   :   China | Japan

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